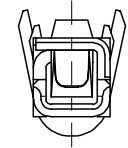
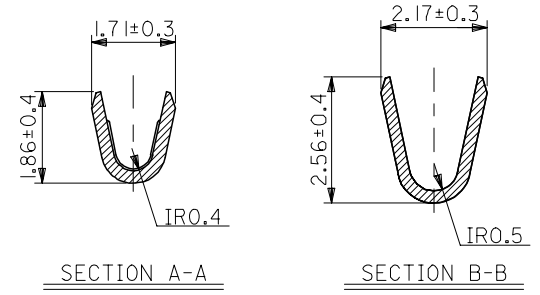


- 注)
NOTES
1. 材質 : りん青銅 t0.25
MATERIAL : PHOSPHOR BRONZE t0.25
 2. メッキ仕様
PLATING
接点部 : 金メッキ 0.3μmMIN.
CONTACT AREA : GOLD 0.3μmMIN.
圧着部 : 錫メッキ 1.0μmMIN.
CRIMP AREA : TIN 1.0μmMIN.
下地メッキ : ニッケルメッキ 2μmMIN.
UNDER PLATING : NICKEL 2μmMIN.
 3. 適用圧着ハウジング : 51209-1001
APPLICABLE CRIMP HOUSING : 51209-1001
 4. 適用電線範囲 : AWG #22 - #28
APPLICABLE WIRES : AWG#22 - #28
 5. 被覆外径 : φ1.2mmMAX.
INSULATION O.D : φ1.2 mmMAX.
 6. 適用圧着工具 (手動) : 57401-5300
APPLICABLE CRIMP TOOL (HAND) : 57401-5300
(半自動) : 57401-3000
(SEMI-AUTOMATIC) : 57401-3000
 7. 適用引抜工具 : 57401-6000
APPLICABLE EXTRACTION TOOL : 57401-6000
 8. 本製品は 59351-8*87 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 59351-8*87.



バラ状 LOOSE	59351-8128	59351-****
連鎖状 CHAIN	59351-8028	
端子形状 TERMINAL CONFIGURATION	MATERIAL NO.	MODEL NO.

RELEASED EC NO: J2007-0955 DRWN: NABEI 2006/10/02 CHKD: TOYODA 2006/10/05 APPR: NUKITA 2006/10/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. NABEI	DATE '06/09/29	TITLE 2.0 I/O CRIMP TERMINAL			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE '06/09/29	-LEAD FREE-			
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE '06/09/29	MOLEX MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.			
0	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-59351-003		1 OF 1
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								